

Bill of Materials

This BOM is for TI Designs TIDA-00185

Item	Qty	Reference	Description	Manufacturer P/N	Manufacturer	Size	Value	Tolerance	Power Rating	Voltage Rating	Temp Coeff
1	1	J7	BATTERY HOLDER 2MM PITCH	2011P02V000	LEOCO		2011P02V000				
2	1	J8	CONNECTOR DB9 MALE	5747841-4	ANY ROHS		5747841-4				
3	1	J6	DC JACK	P002-3100-000-Z	SMP Technology		P002-3100-000-Z				
4	4	J1-3 J10	HEADER 2-PIN 2MM PITCH	NRPN021PAEN-RC	Sullins		NRPN021PAEN-RC				
5	1	U1	IC LMX9838 BLUETOOTH SERIAL PORT MODULE	LMX9838	NATIONAL SEMICONDUCTOR		LMX9838				
6	1	U3	IC LP3985 3.3V VOLTAGE REGULATOR	LP3985IM5X-3.3	NATIONAL SEMICONDUCTOR		LP3985-3.3V				
7	1	U2	IC MAX3225 RS232 TRANSCEIVER	MAX3225EEAP+	MAXIM		MAX3225				
9	4	C1 C3 C8 C10	CHIP CAPACITOR	GRM39Y5V104Z50	ANY	603	100NF	Z%		50V	Y5V
10	1	C9	CHIP CAPACITOR	GRM39C0G101J50	ANY	603	100PF	J%		50V	C0G
11	5	C13-17	CHIP CAPACITOR	GRM42-6X7R105K25	ANY	1206	1UF	K%		25V	X7R
12	1	C19	CHIP CAPACITOR	GRM39Y5V105Z10	ANY	603	1UF	Z%		10V	Y5V
13	3	C2 C4 C7	CHIP CAPACITOR	GRM39Y5V225Z10	ANY	603	2.2UF	Z%		10V	Y5V
14	2	C5-6	CHIP CAPACITOR	GRM39C0G220J50	ANY	603	22PF	J%		50V	C0G
16	1	D2	SMD LED BLUE		ANY		BLUE				
17	1	D1	SMD LED RED		ANY		RED				
18	7	R6-9 R13-14 R17	CHIP RESISTOR		ANY	603	0R	5%	1/16W		
19	2	R11-12	CHIP RESISTOR		ANY	603	10K	5%	1/16W		
20	3	R1-3	CHIP RESISTOR		ANY	603	1K	5%	1/16W		
21	2	R4-5	CHIP RESISTOR		ANY	603	330R	5%	1/16W		
23	2	C11-12	TANTALUM CAPACITOR		ANY	A-SIZE	1UF	Z%		16V	
24	1	J4	SOCKET 6-PIN 2MM PITCH	25630601RP2	Norcomp		25630601RP2				
30	1	S1	TACT SWITCH	TL3330AF130QG	eswitch		TL3330AF130QG				
31	1	Y1	TUNING FORK CRYSTAL 32.768KHZ				32.768KHZ				
32	1	J9	SMA 50 Ohm connector	142-0711-821	Johnson Components		DNI				
33	1	C18	Capacitor 8p2 COG 50V	GRM39COG8R2J50	MuRata	603	DNI	J%		50V	C0G

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